

## Rigid Flex / Semi Flex PCB Stackup

Layer	Cu Thick. (mils)	Cu Foil wt (oz)	DK	Lam. Thick. (mils)	Description
1	1.55	.375 oz			Foil .375 oz
2	0.65	.375 oz	3.41	2.61	Prepreg I-Speed 1067(74) 18.25Gx24.25 Foil .375 oz
3	0.65	.375 oz	3.56	3.24	Prepreg I-Speed 1086(66.5) 18.25Gx24.25 Foil .375 oz
4	0.60	.5 oz	3.49	3.83	Prepreg I-Speed 1086(70) 18.25Gx24.25 Foil .5 oz
5	0.60	0.5 oz	3.42	3.75	Prepreg I-Speed 1078(73.5) 18.25Gx24.25
6	0.60	0.5 oz	1.85	2.00	Polyimide
7	0.60	0.5 oz	1.85	2.00	Polyimide
8	0.60	0.5 oz	3.42	3.75	Prepreg I-Speed 1078(73.5) 18.25Gx24.25
9	0.60	.5 oz	3.49	3.83	Prepreg I-Speed 1086(70) 18.25Gx24.25 Foil .5 oz
10	0.65	.375 oz	3.56	3.41	Prepreg I-Speed 1086(66.5) 18.25Gx24.25 Foil .375 oz
11	0.65	.375 oz	3.41	2.61	Prepreg I-Speed 1067(74) 18.25Gx24.25 Foil .375 oz
12	1.55	.375 oz			Foil .375 oz

**Special Requirement:**

- A: Blind Via spans
- B: Buried Via spans
- C: 4 Layer Flex with 8 layers Rigid laminations

41.23 Thickness over Laminate  
 44.33 Thickness over Copper  
 45.33 Thickness over Soldermask